Sil-Pad® A2000

Higher Performance, High Reliability Insulator

Features and Benefits

- Thermal impedance: 0.32°C-in²/W (@50 psi)
- · Optimal heat transfer
- · High thermal conductivity: 3.0 W/m-K



SI-Pad A2000 is a conformable elastomer with very high thermal conductivity that acts as a thermal interface between electrical components and heat sinks SI-Pad A2000 is for applications where optimal heat transfer is a requirement.

This thermally conductive silicone elastomer is formulated to maximize the thermal and dielectric performance of the filler/binder matrix. The result is a grease-free, conformable material capable of meeting or exceeding the thermal and electrical requirements of high reliability electronic packaging applications

TYPICAL PROPERTIES OF SIL-PAD A2000						
PROPERTY	IMPERIALVALUE		METRIC VALUE		TEST METHOD	
Color	White		W hite		Visual	
Reinforcement Carrier	Fiberglass		Fiberglass		_	
Thickness (inch) / (mm)	0.015 to 0.020		0.381 to 0.508		ASTM D374	
Hardness (Shore A)	90		90		ASTM D2240	
Heat Capacity (Jg-K)	1.0		1.0		ASTM E1269	
Continuous Use Temp (℉) / (℃)	-76 to 392		-60 to 200		_	
ELECTRICAL						
Dielectric Breakdown Voltage (Vac)	4000		4000		ASTM D149	
Dielectric Constant (1000 Hz)	7.0		7.0		ASTM D150	
Volume Resistivity (Ohm-meter)	10 ¹¹		10 ¹¹		ASTM D257	
Flame Rating	V-O		V-O		U.L.94	
THERMAL						
Thermal Conductivity (W/m-K)	3.0		3.0		ASTM D5470	
THERMAL PERFORMANCE vs PRESSURE						
Press	sure (psi)	10	25	50	100	200
TO-220 Thermal Performance (℃/W) 0.015"		2.05	1.94	1.86	1.79	1.72
Thermal Impedance (°C-in²/W) 0.015" (1)		0.53	0.40	0.32	0.28	0.26
1) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for						

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Typical Applications Include:

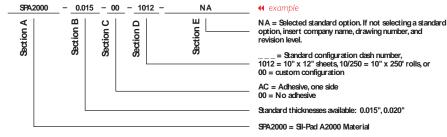
- Motor drive controls
- Avionics
- High-voltage power supplies
- · Power transistor / heat sink interface

Configurations Available:

- · Sheet form, die-cut parts and roll form
- · With or without pressure sensitive adhesive

Building a Part Number

Standard Options



Note: To build a part number, visit our website at www.bergquistcompany.com.

SI-Pad®: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others